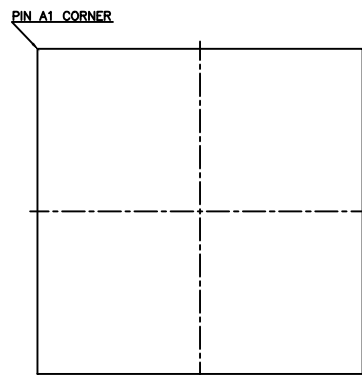
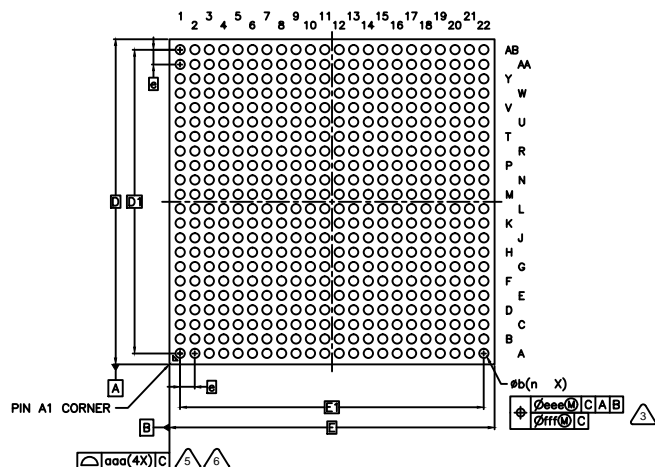
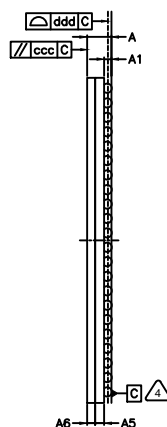


TOP VIEW



SIDE VIEW



BOTTOM VIEW

	Symbol	Common Dimensions		
		MIN.	NOM.	MAX.
Package:		MFC LFBGA		
Body Size:	X	E	18.000	
	Y	D	18.000	
Ball Pitch:	e	0.800		
Total Thickness:	A	1.225	1.344	1.463
Mold Cap Thickness:	A6	0.450		Ref.
Substrate Thickness:	A5	0.494		Ref.
Ball Diameter:		0.500		
Stand Off:	A1	0.300	0.400	0.500
Ball Width:	b	0.450	0.500	0.550
Package Edge Tolerance:	aaa	0.150		
Mold Parallelism:	ccc	0.200		
Coplanarity:	ddd	0.200		
Ball Offset (Package):	eee	0.150		
Ball Offset (Ball):	fff	0.080		
Ball Count:	n	484		
Edge Ball Center to Center:	X	E1	16.800	
	Y	D1	16.800	

NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. JEDEC REFERENCE: JEP95 DR4.5

Title: Package Outline Drawing		Pkg Type: FCCSP	Document No: POD-250013	
Product Family: LAV-AT		Pin Count: 484		
Product Name: LAV-AT-E30C-CBG484 LAV-AT-E30B-CBG484		Pkg Size: 18x18 mm	Rev: C	PAGE: 3/3
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